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Manufacturer's Letter

Date: October 17, 2006

American Telecommunications Certification Body, Inc.
6731 Whittier Avenue
Suite C110
McLean, VA 22101

RE: Certification Application
FCC ID: N6C-SX10WG

To Whom It May Concern:

Please be advised that the manufacturer will ensure that the above-referenced model will be manufactured in accordance with the FCC Rules and Regulations.

Thank you for your attention to this matter.

Sincerely,

A handwritten signature in cursive script that reads "Toshiro Kometani".

Toshiro Kometani
Manager
2nd Group, Hardware Engineering Division
R&D Center



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FCC Labeling Requirements and Information

Date October 17, 2006

American Telecommunications Certification Body, Inc.
6731 Whittier Avenue
Suite C110
McLean, VA 22101

RE: FCC Labeling Requirements
FCC ID: N6C-SX10WG

The following label information is required by the FCC Rules and Regulations for certified devices. Also attached, please find marketing information required by the FCC Rules and Regulations.

Thank you for your attention to these matters.

Sincerely,

A handwritten signature in cursive script that reads "Toshiro Kometani".

Toshiro Kometani
Manager
2nd Group, Hardware Engineering Division
R&D Center

Letter Of Agency

Date: October 17, 2006

American Telecommunications Certification Body, Inc.
6731 Whittier Avenue
Suite C110
McLean, VA 22101

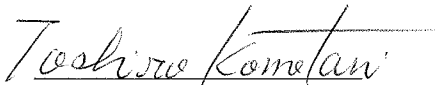
To Whom It May Concern:

Please be advised that silex technology, Inc. authorizes UL Apex Co., Ltd. to act on our behalf, until otherwise notified, for applications submitted to American Telecommunications Certification Body, Inc. (ATCB).

We certify that we are not subject to denial of federal benefits, that includes FCC benefits, pursuant to Section 5301 of the Anti-Drug Abuse ACT of 1988, U.S.C. 862. Further, no party, as defined in 47 CFR 1.2002(b), to the application is subject to denial of federal benefits, that includes FCC benefits.

Thank you for your attention to this matter.

Sincerely,



Toshiro Kometani
Manager
2nd Group, Hardware Engineering Division
R&D Center